



Disclaimer

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Company Profile

Established	May 24, 1996
Capital	NTD 842 Million (USD 27 Million)
Business	Automation equipment supplier for Semiconductor test & package, Passive Component manufacturing and LED back-end industries
Employee	206 (JAN, 2017)
Chairman	Larry Lu
Address	No.1 Luke 10th Rd. ,Lujhu,Kaohsiung,Taiwan
Website	www.allring-tech.com.tw

Global Operation Site



Headquarters:
Kaohsiung/Taiwan



Subsidiary :
Kunshan/Jiangsu



Industry Overview

Electronic Device



Compact Size/Multiple



**Component
Miniaturization**



**Sub-system
Modularization**

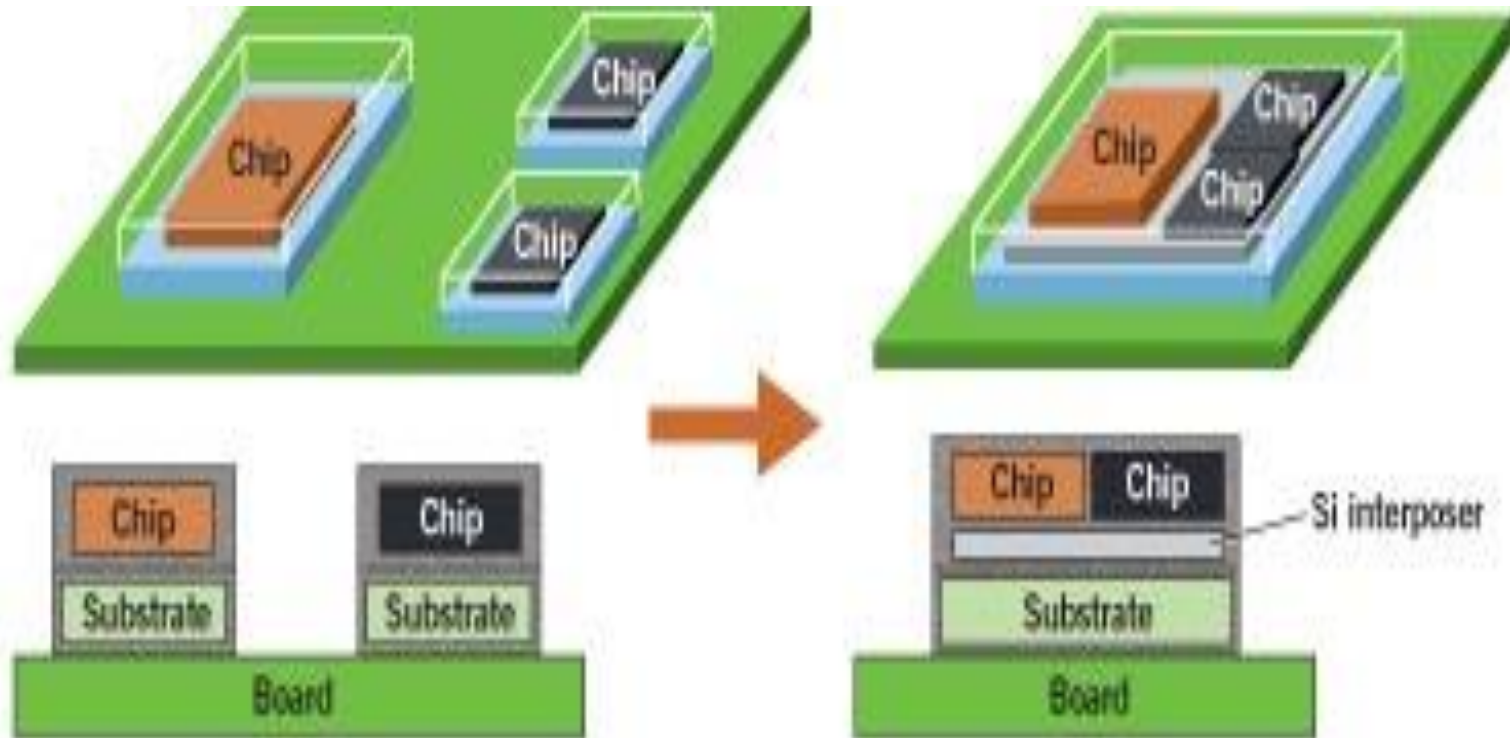


**Advance
Package**

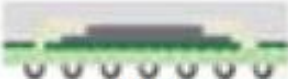
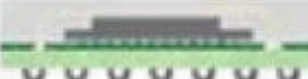
Advance Package

Packaging Type		Figure	Manufacturer		Application
SIP (system in package)		Page 7,8	OSAT	ASE	Smart phone IoT Mobile
				USI	
			Module house	Hon Hai	
				Pegatron	
			Component	AAC	
				Largan	
WLP (wafer level package)	InFO	Page 9	Foundry	TSMC	Smart Phone
	CoWoS			TSMC	
Flip chip	2D/3D	Page 10	OSAT	ASE	Smart Phone IoT Mobile
				Spil	
				Amkor	
				JCET	
				Powertech	

System in Package (SiP)

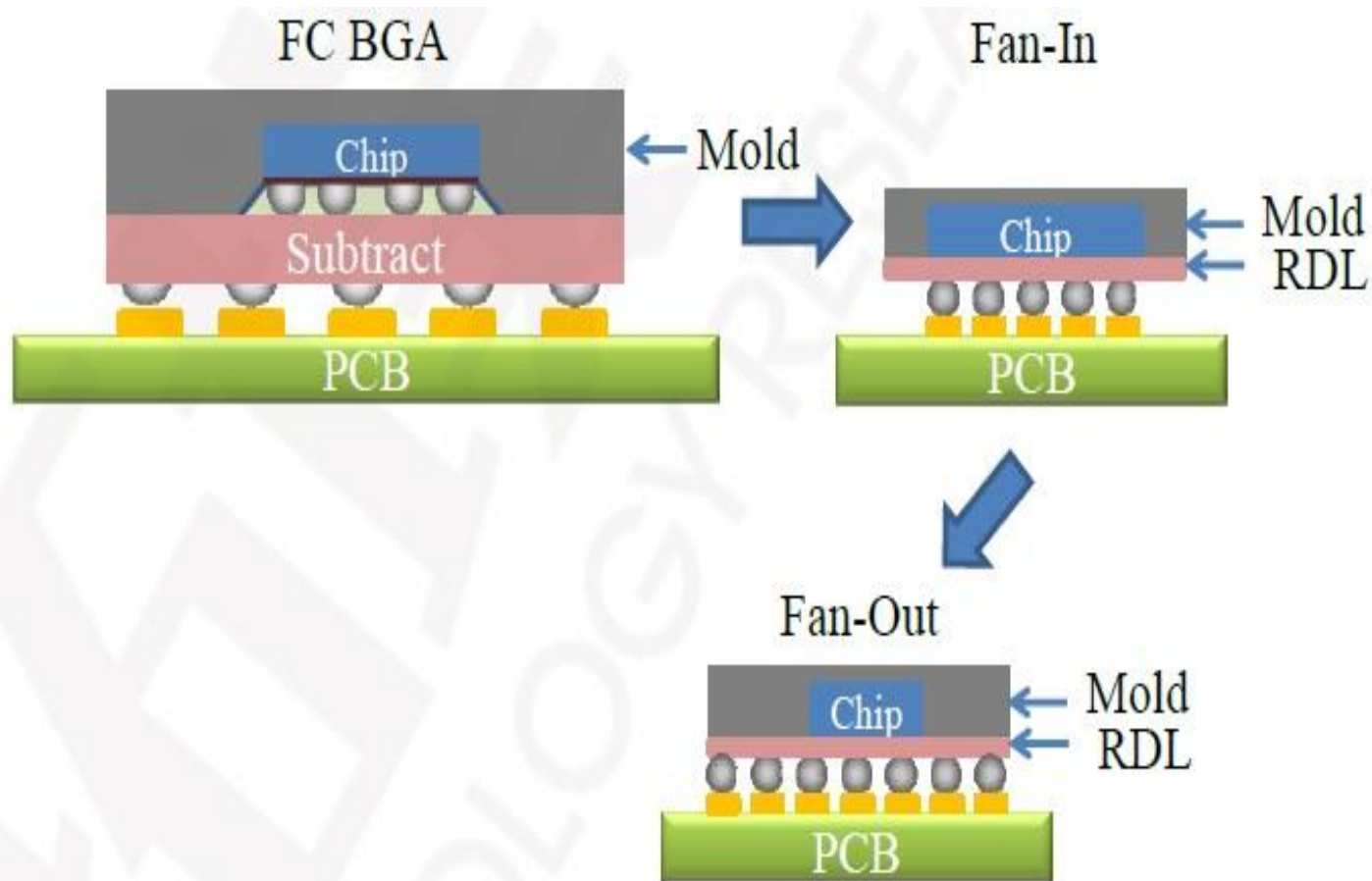


Basic Types of SiP

Package Structure	Solutions
Horizontal Placement 	 W/B  Flip Chip
Stacked Structure 	 W/B  W/B+FC  PiP, PoP
Embedded Structure 	 LTCC  Embedded Passives  IPD
Advanced Technology  Chip Scale Module	 Embedded Chip  Multi-Chip Fan-Out WLP  2.5D Interposer
	 TSV  3D Fan-Out WLP

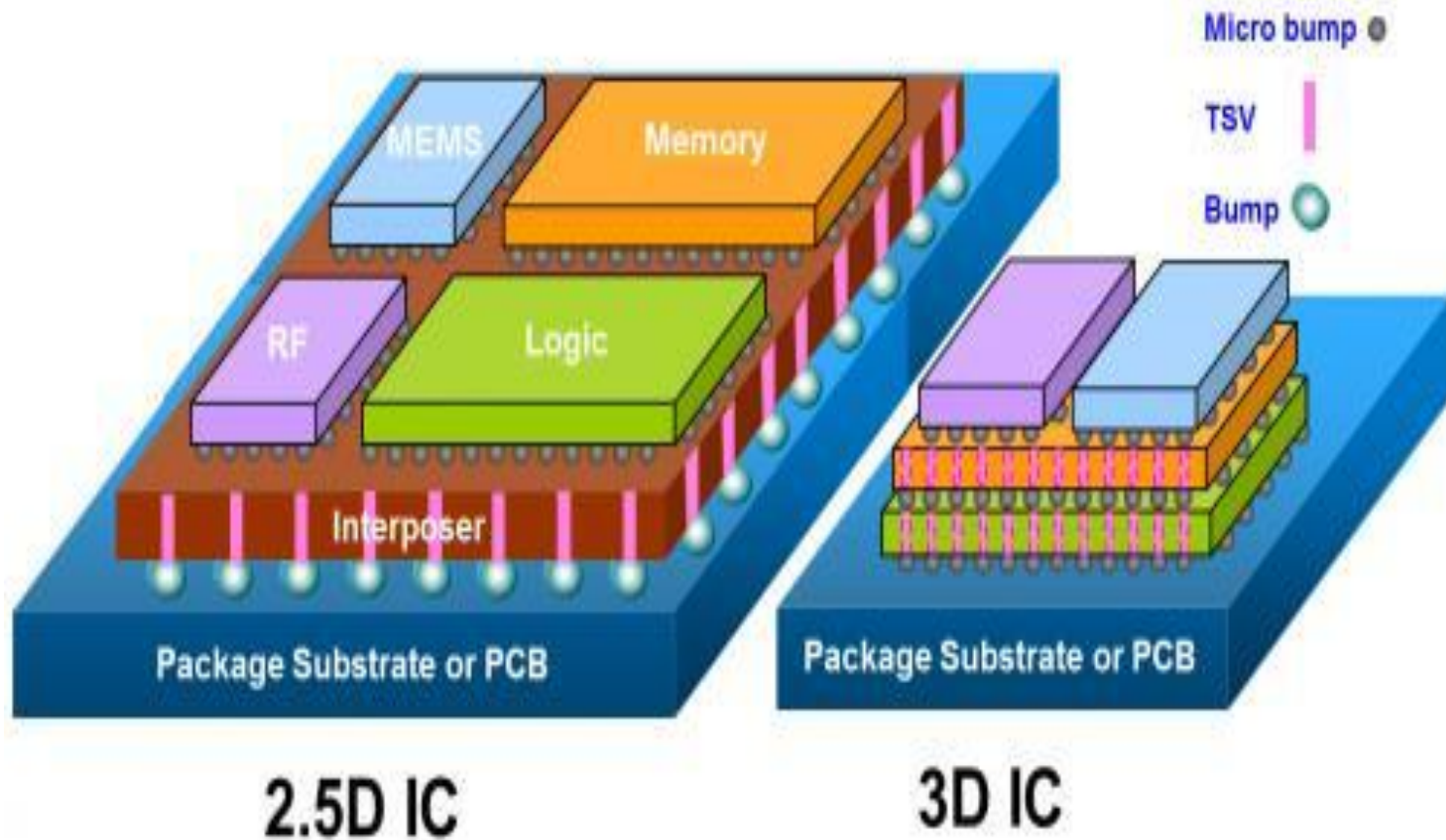
Source: TRI

Flip-chip & wafer-level packaging

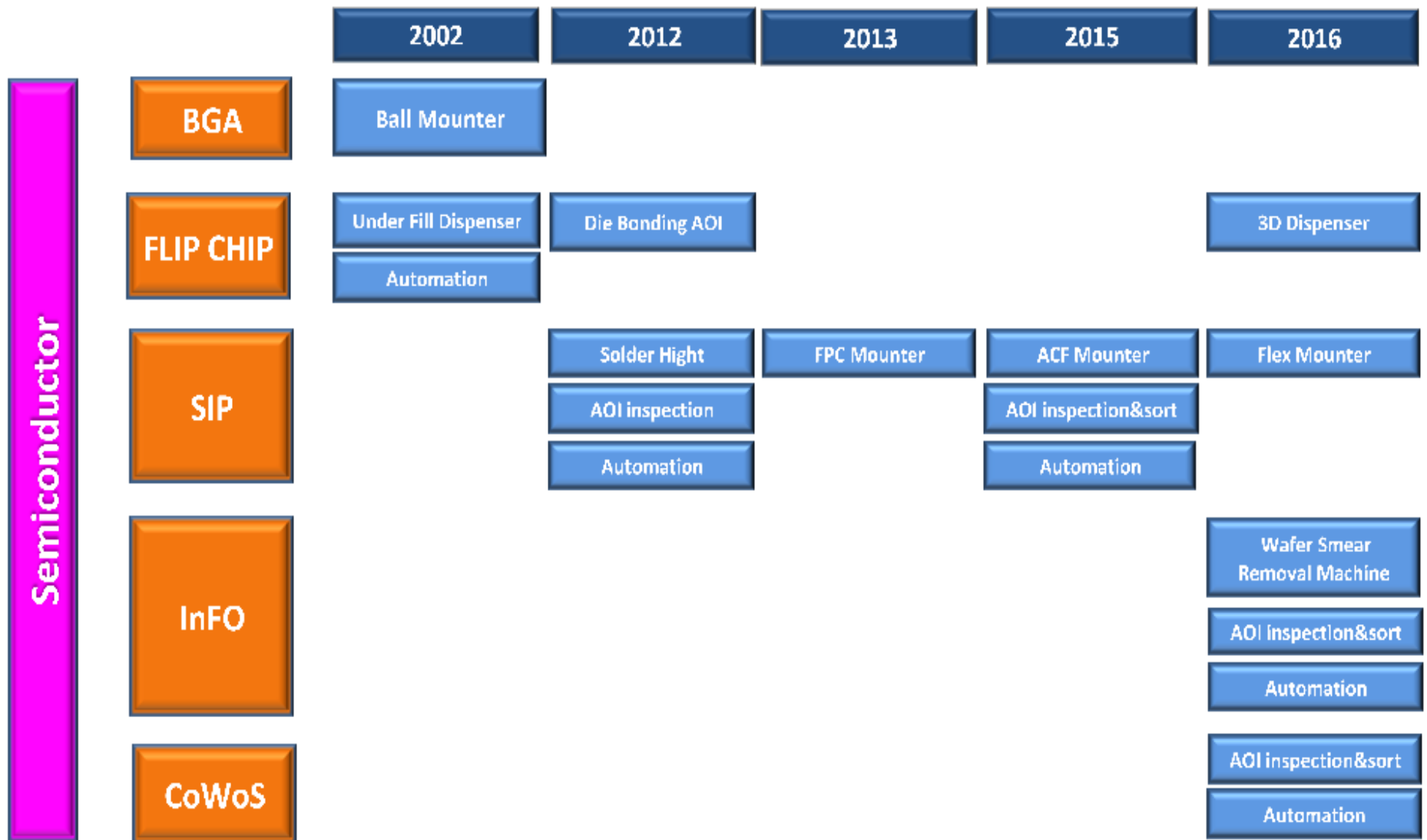


Source: TRI

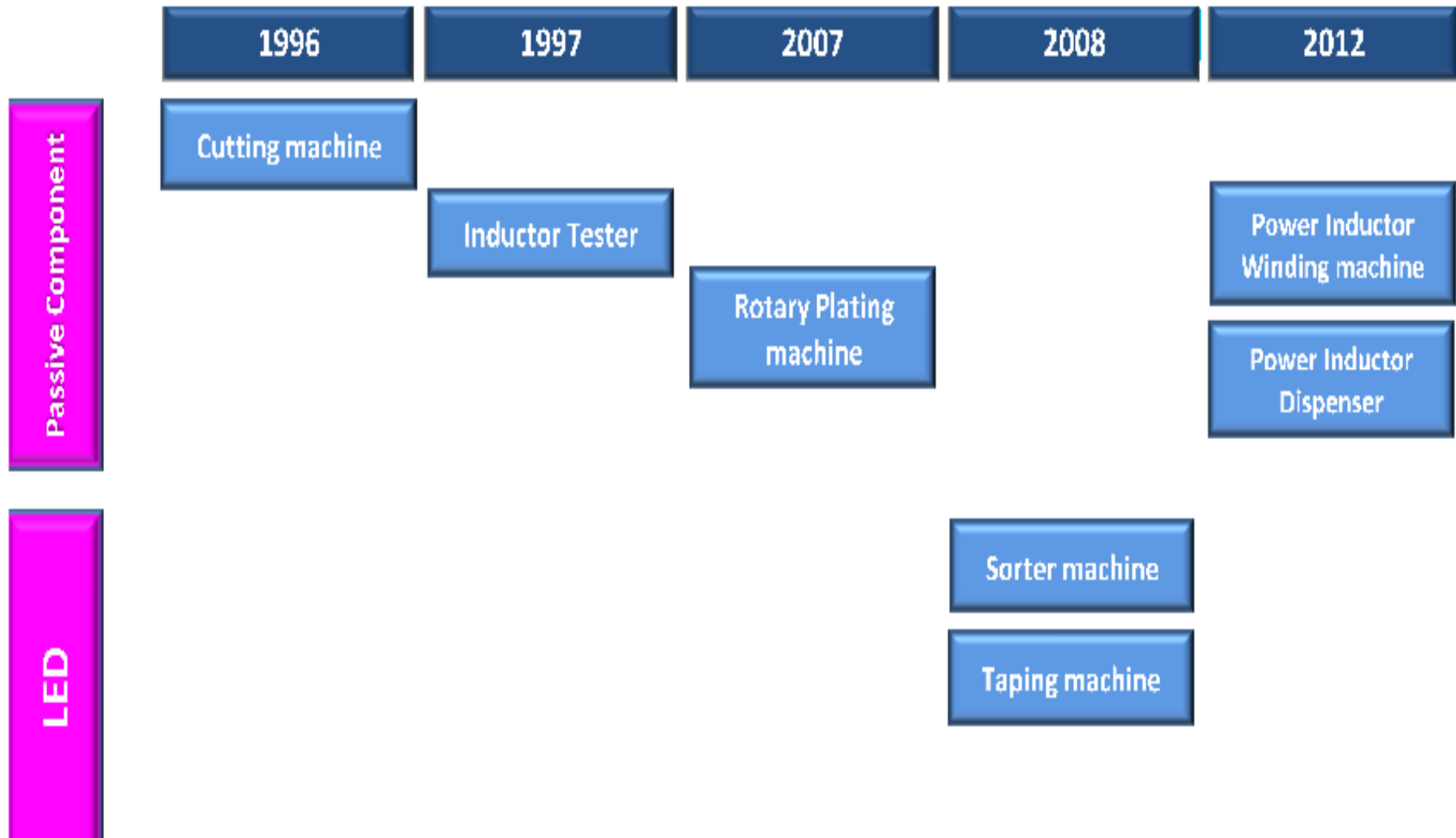
2.5D & 3D IC Packaging



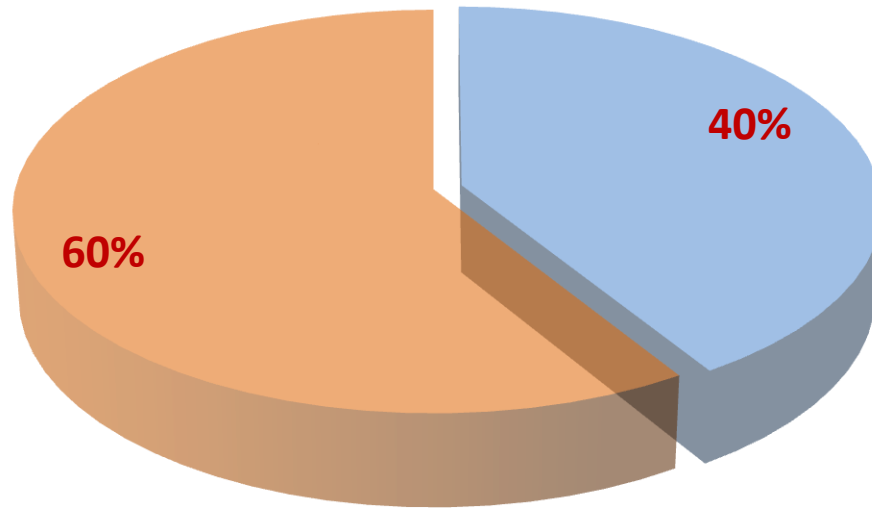
Product Portfolio—Semiconductor



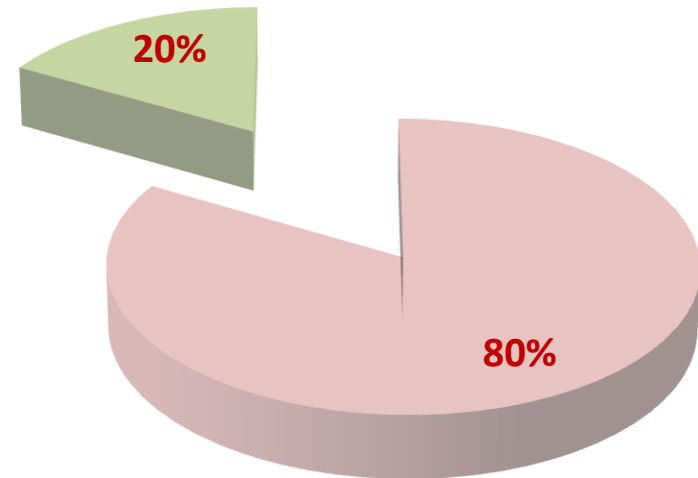
Product Portfolio—Passive Component/LED



Human Resources- R&D Background



■ Hardware
■ Software



■ Motion Programming
■ Visual System

Dispensing Pump (Valve) Line-Ups

Dispensing
Control

0.1mg $\pm$ 5%

INK- Jet Printer

Piezoelectric Jetting Pump

Jetting
Pump

Linear Pump

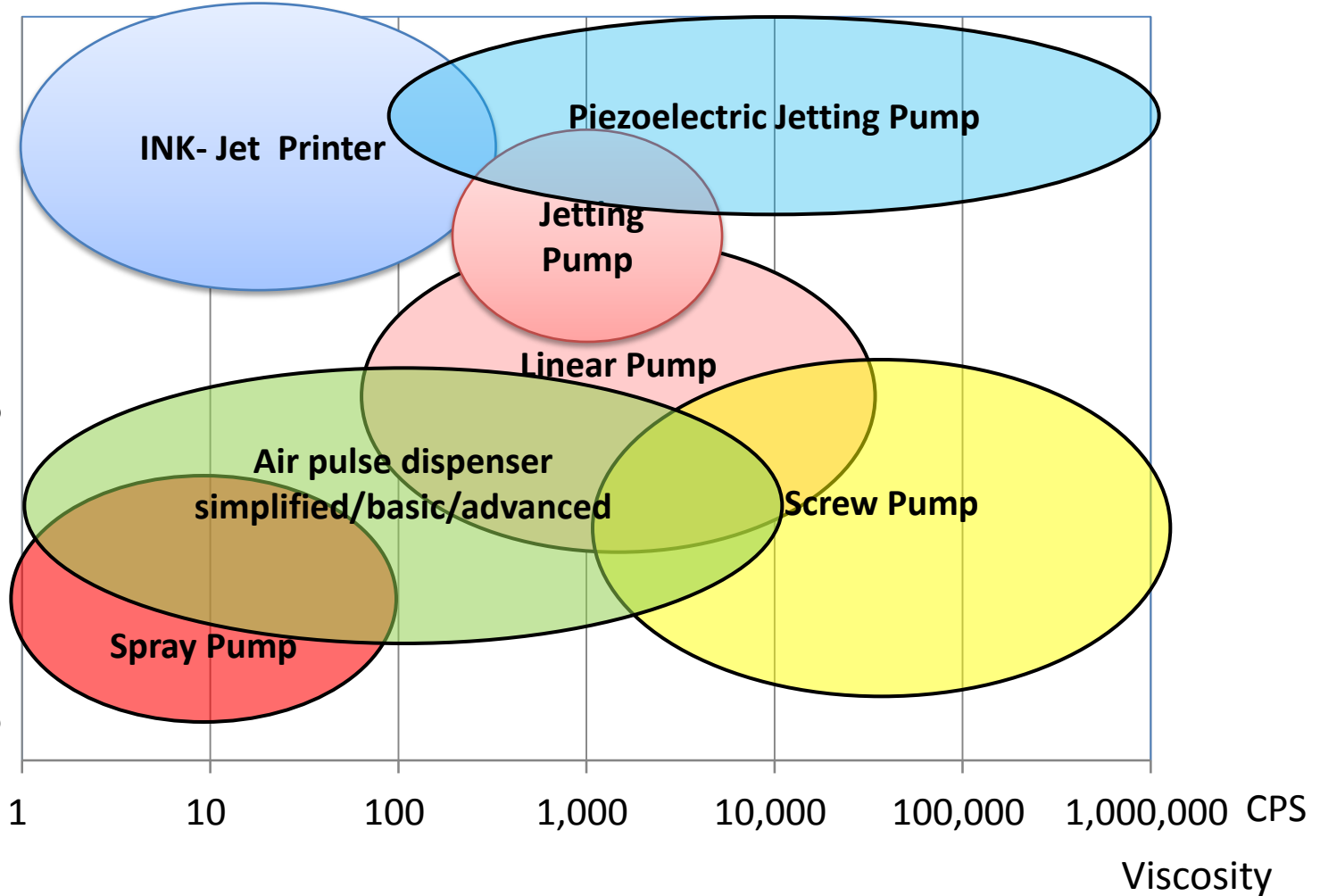
1mg $\pm$ 5%

Air pulse dispenser
simplified/basic/advanced

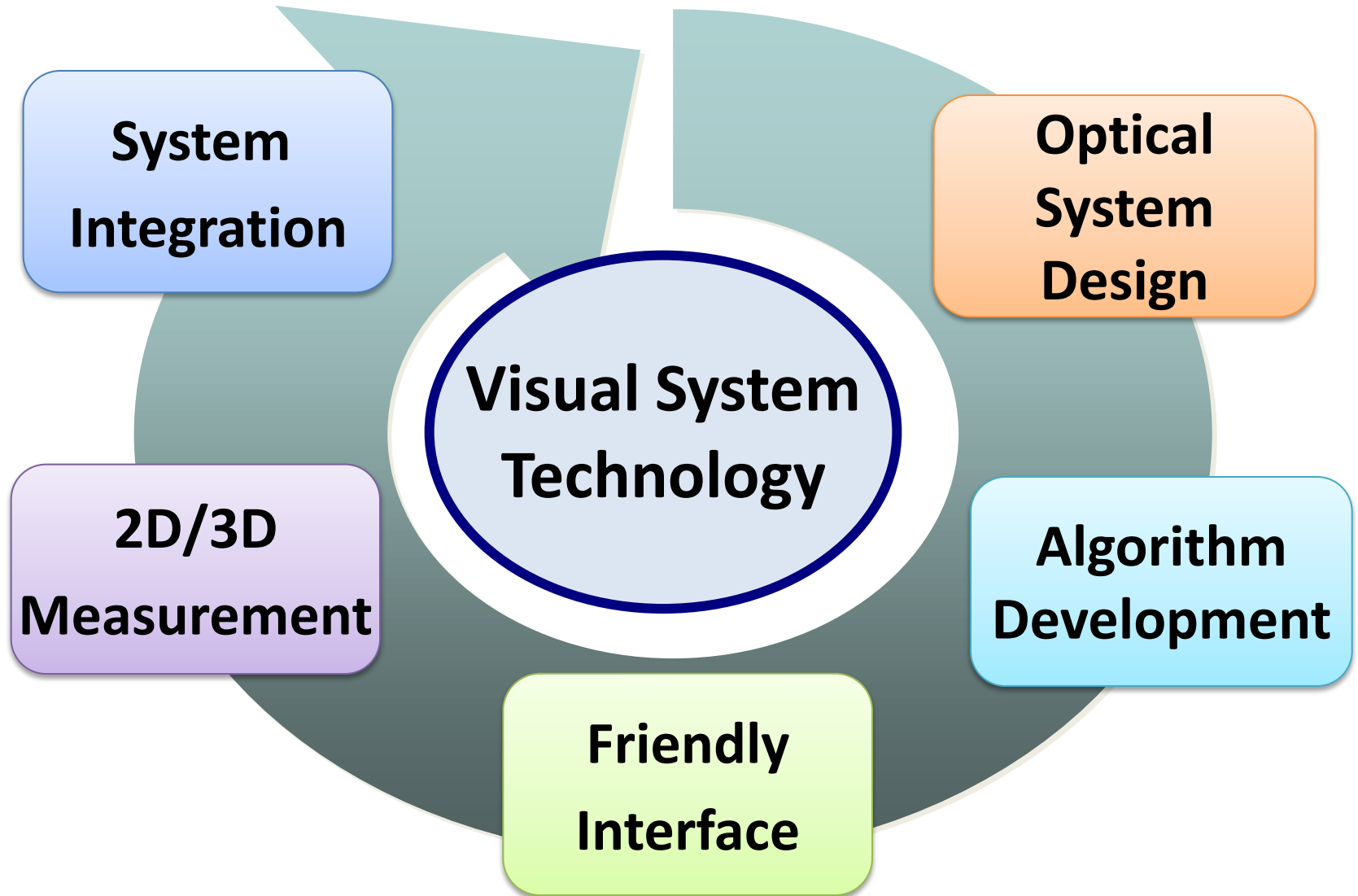
Screw Pump

10mg $\pm$ 5%

Spray Pump



Visual System Technology



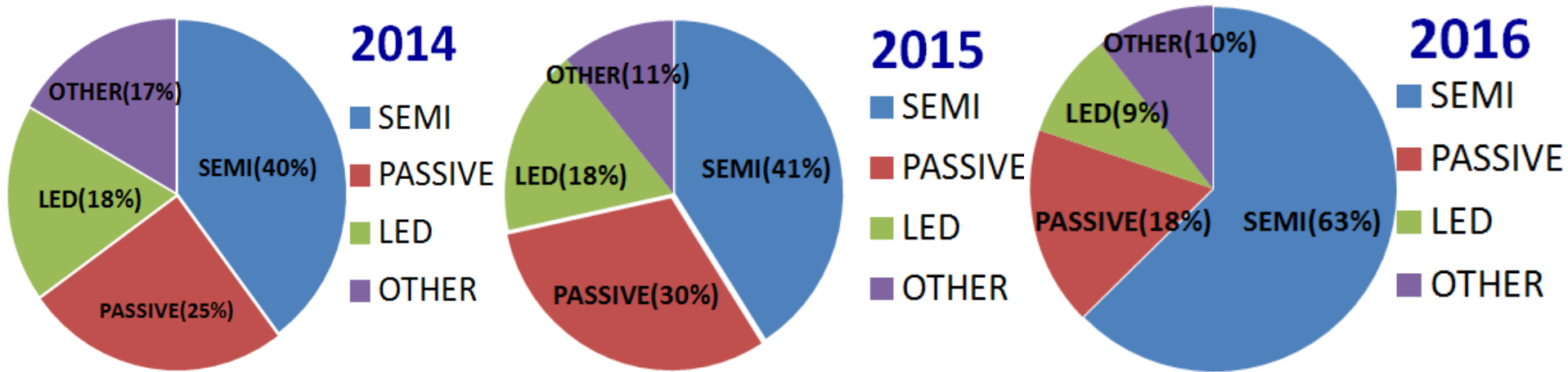
Numbers of Patents

Market Segment	Granted	Pending
Semiconductor	51	28
Passive Component	58	29
LED	12	22
FPD	7	0
Other	9	2
PCB	0	5
TOTAL	137	86

Customer Base

Semiconductor	Passive Component	LED
      	           	     

Revenue Breakdown



NT\$100M

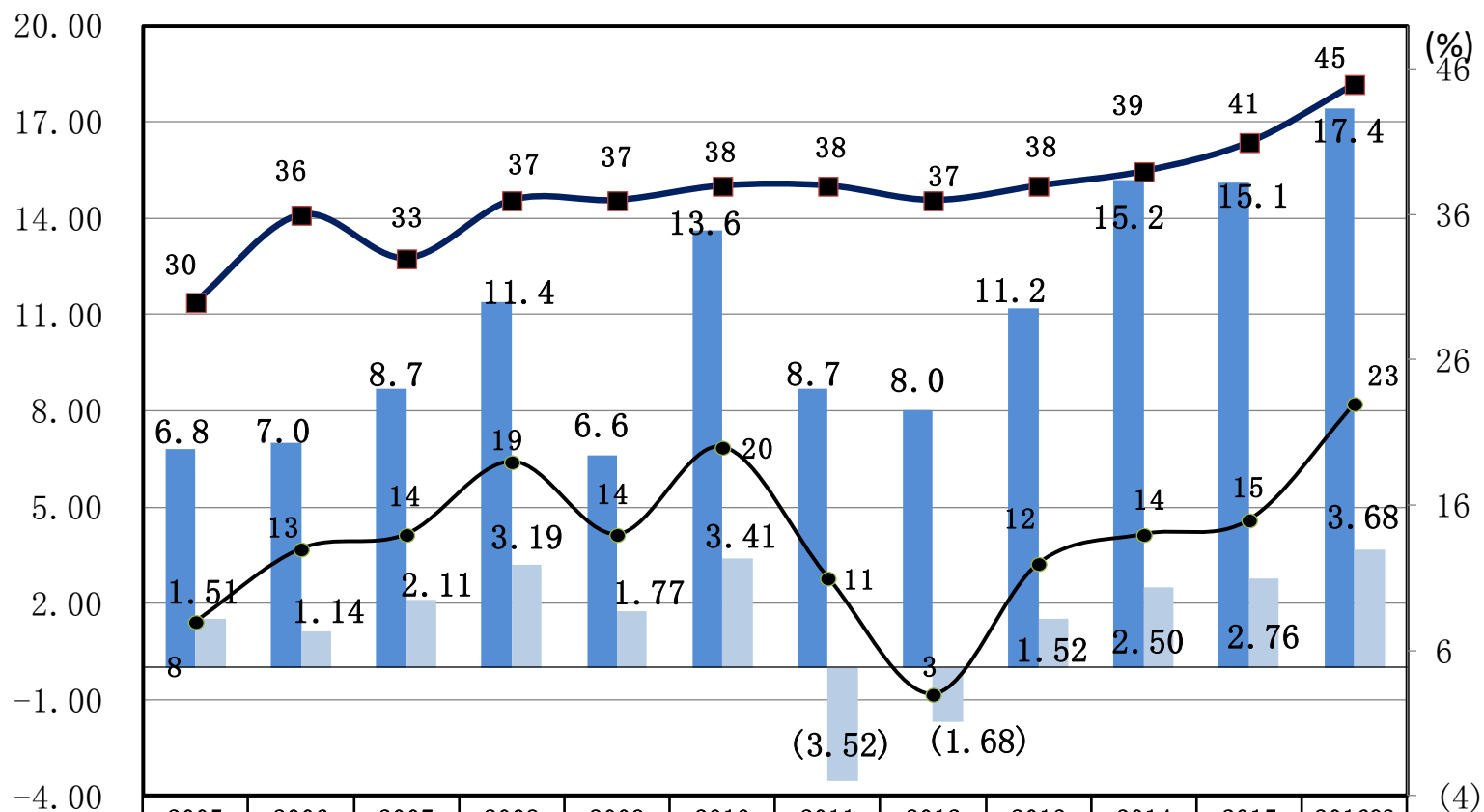
2014

2015

2016

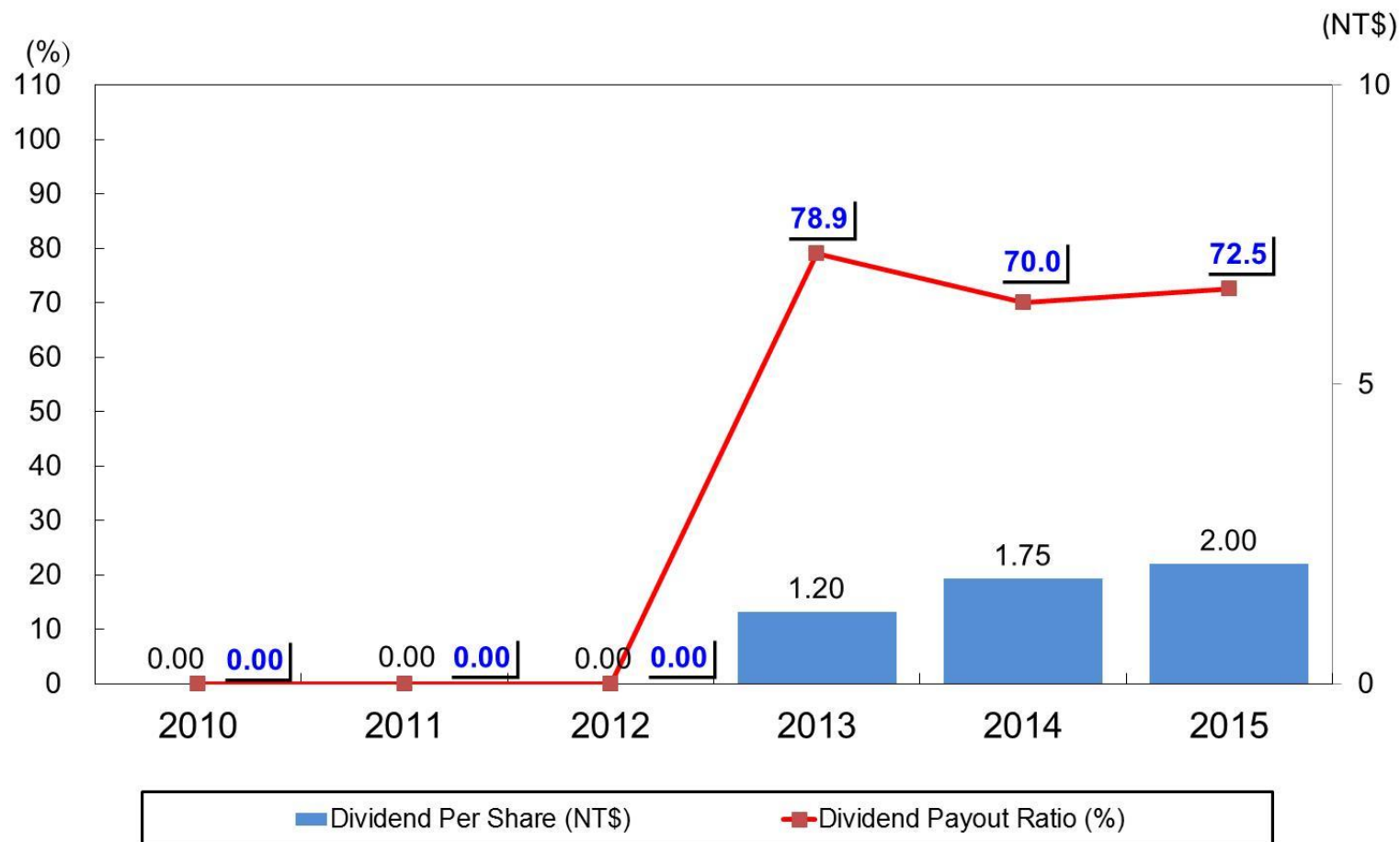
SEMI	6.04	40%		6.17	41%		13.23	63%
PASSIVE	3.69	25%		4.62	30%		3.70	18%
LED	2.77	18%		2.64	18%		1.97	9%
OTHER	2.69	17%		1.64	11%		2.22	10%
TOTAL	15.19	100%		15.07	100%		21.12	100%

Financial Highlights

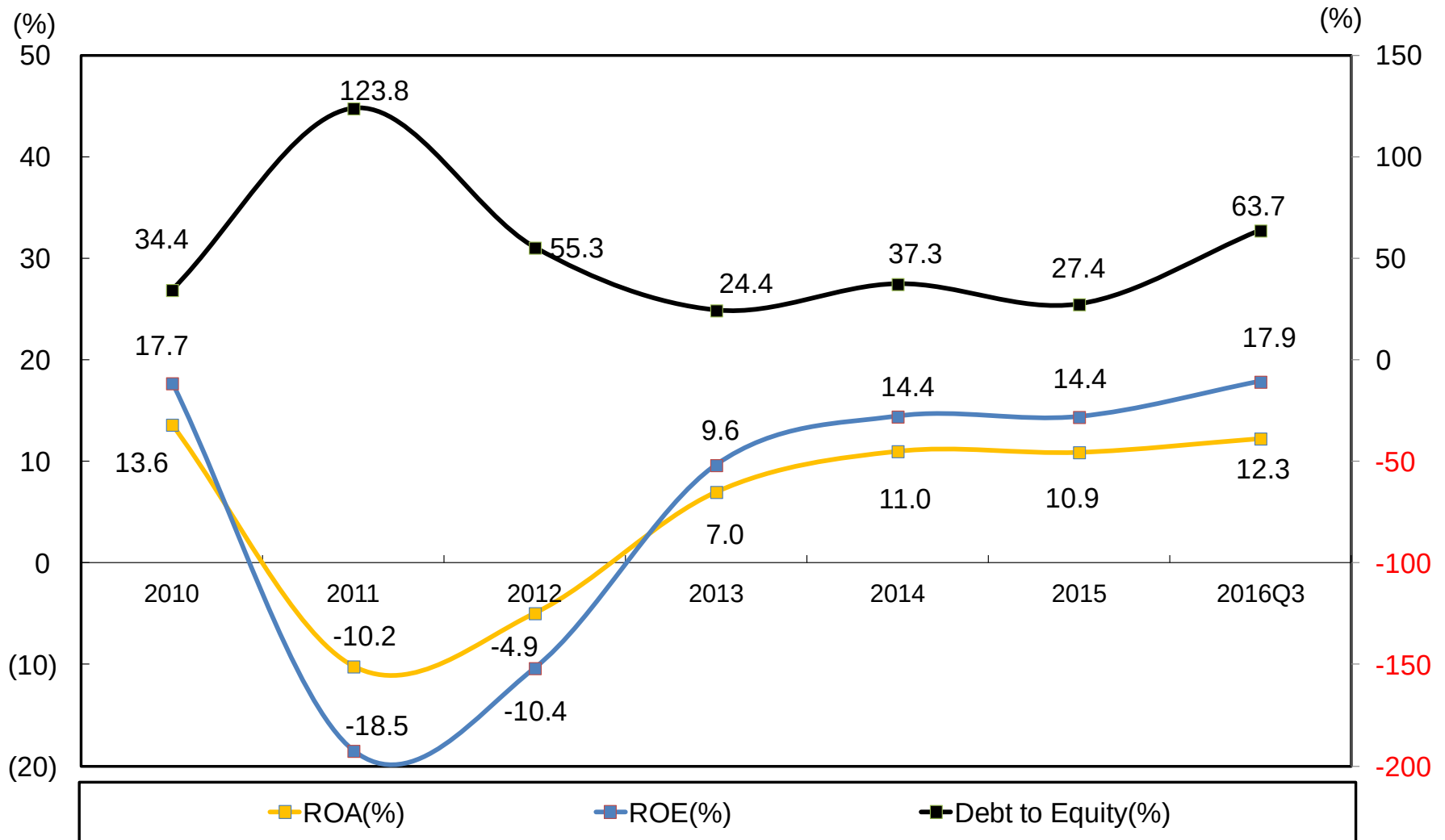


	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016Q3
Sales (NT\$100mn)	6.8	7.0	8.7	11.4	6.6	13.6	8.7	8.0	11.2	15.2	15.1	17.4
EPS (NT\$)	1.51	1.14	2.11	3.19	1.77	3.41	(3.52)	(1.68)	1.52	2.5	2.76	3.68
GM (%)	30	36	33	37	37	38	38	37	38	39	41	45
OPM (%)	8	13	14	19	14	20	11	3	12	14	15	23

Financial Highlights



Financial Highlights



Q & A

